

PRODUCT NUMBER
90309-XXXXLF

PLATING _____

0 = 0.20µm GOLD/GXT ON CONTACT AREA
2µm MIN MATTE TIN ON TAIL

1 = 0.76µm GOLD/GXT ON CONTACT AREA
2µm MIN MATTE TIN ON TAIL

3 = 0.38µm GOLD/GXT ON CONTACT AREA
2µm MIN MATTE TIN ON TAIL

5 = 0.38µm GXT FULL PLATED

6 = 0.76µm GXT FULL PLATED

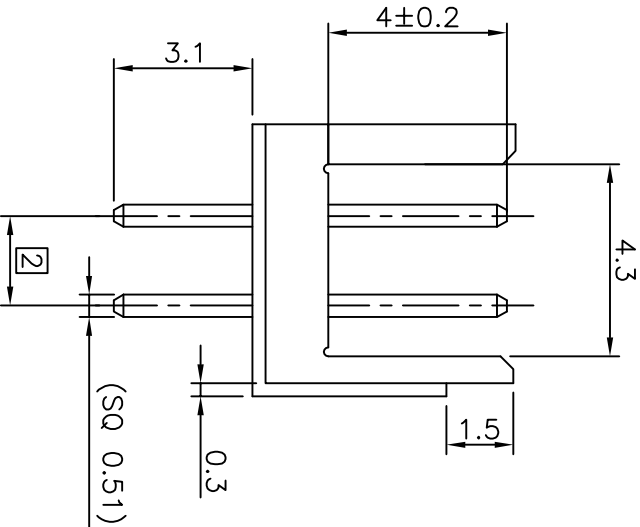
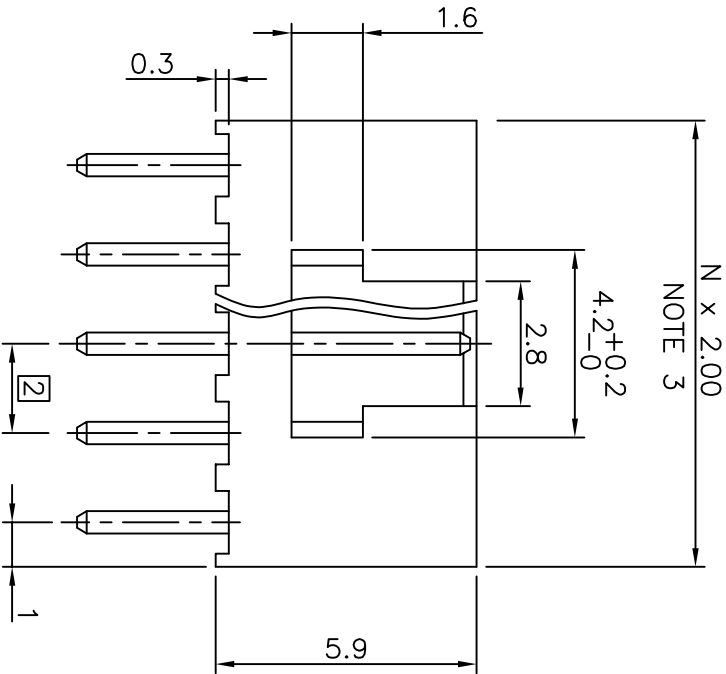
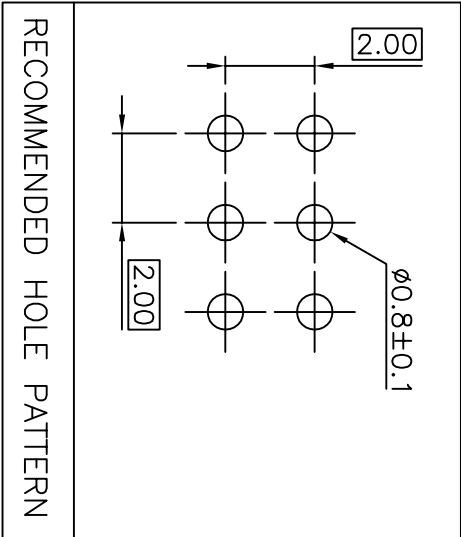
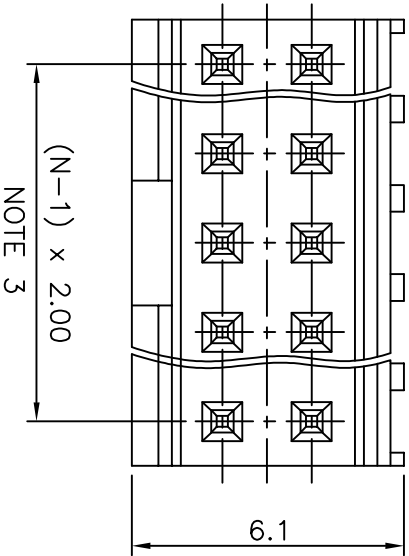
7 = 0.76µm GOLD/GXT FULL PLATED

9 = 0.20µm GOLD/GXT FULL PLATED

1.27µm Ni MIN DERPLATING

NOTES:

1. MATERIAL HOUSING: HIGH TEMP. THERMOPLASTIC
UL 94V-0, COLOR CREAM
2. MATERIAL TERMINAL: COPPER ALLOY
3. TO DETERMINE DIMENSIONS:
N = NUMBER OF POSITIONS PER ROW
4. 7N MIN. PIN RETENTION IN EITHER DIRECTION.
5. PACKAGING: = POLYBAGS
 T = TUBE
6. RoHS COMPATIBLE PRODUCT SPECIFICATIONS
- a - PLATING:
 - "LF" MEANS THE PRODUCT IS LEAD-FREE,
2µm MINIMUM MATTE TIN OVER 1.27µm
MINIMUM NICKEL UNDERPLATE.
- b - MANUFACTURING PROCESS COMPATIBILITY
 - THE HOUSING WILL WITHSTAND EXPOSURE TO
260°C ±5°C SOLDER BATH TEMPERATURE FOR
5 SECONDS IN A WAVE SOLDER APPLICATION
WITH A 1.6mm MIN THICK CIRCUIT BOARD.
- c - LABELLING:
 - MEETS PACKAGING SPECS AS PER GS-14-920
 - d - THIS PRODUCT MEETS EUROPEAN DIRECTIVES
AND OTHER COUNTRY REGULATIONS AS DISCRIBED
IN GS-47-0004.



mat'l. code				surface		tolerance		projection	product family		
SEE NOTES				ISO 1302	ISO 406	ISO	ISO				
lfr	ecr	no	dr	date	tolerances unless otherwise specified			mm	MINITEK HEADER		title
S	F05-0128	LMU	05.02.21		angles	linear	.X				
T	F06-0210	LMU	06.07.04				.XX	±0.13	SHR HEADER		2.00mm TWT DR
U	F07-0191	JCO	07.09.05	±2°			.XXX	±0.05			
V	F08-0145	ELA	15.04.08	dr	JL.CORDIER			97.07.26	FCI		sheet 1 of 1
W	B-19190	LMU	14.10.24	eng	JL.COMPAGNON			97.07.26			
				chr	JL.CORDIER			97.07.26	CUSTOMER Drawing		size
				appd	JMC			97.07.26			
sheet index	revision	sheet									